



DELTA SOLDER

PRINT BRICKS EVERY TIME



Lead Free Formulations:

Delta Solder Paste is a unique blend of low oxide, highly pure solder powders combined with various patented paste flux formulations. Whether your surface mount assemblies require No-Clean, Water-Soluble or RMA (Rosin Mildly Activated), type solder paste. Delta Solder Paste is the right choice to achieve high productivity and reduce production cost.

DSP 825HF No-Clean Solder Paste Stencil Printing

Alloys: Ecolloy, SAC alloys, Sn96.5/Ag3.5, Sn95/Ag5, Sn95/Sb5

- ROL0 Flux classification
- Halogen -Free
- Excellent wetting and coalescence
- Enhanced fine pitch printing
- Temperature stable no refrigeration required

DSP 866 No-Clean Solder Paste Stencil Printing

Alloys: SAC alloys

- ROL0 Flux classification
- Zero halogen
- Low voiding
- Pin probable

DSP 875 No-Clean Solder Paste Stencil Printing

Alloys: SAC alloys

- REL0 Flux classification
- Halogen-Free
- Superior low flux spatter
- Excellent wettability

DSP 618D No-Clean Solder Paste Syringe Dispensing

Alloys: SAC alloys, Sn100e

- ROL0 Flux classification
- Easily dispensed
- Hard, non-conductive residues
- Designed specifically for lead-free applications

DSP 230 R.M.A. Solder Paste Stencil Printing

Alloys: Sac alloys

- ROM0 Flux classification
- Designed for fine pitch printing
- Yields bright, shiny joints

DSP 215D R.M.A. Solder Paste Syringe Dispensing

Alloys: SAC alloys

- ROM0 Flux classification
- Easily dispensed
- Hard, non-conductive residues

DSP 798LF Water-Soluble Solder Paste Stencil Printing

Alloys: Ecolloy, SAC alloys, Sn96.5/Ag3.5, Sn95/Ag5, Sn42/Bi58

- ORH0 Flux classification
- Enhanced activity for a broad range of applications
- Excellent printing characteristics
- Easy removal of residue

DSP 787LV Water-Soluble Solder Paste Stencil Printing

Alloys: SAC alloys, Sn96.5/Ag3.5

- ORH0 Flux classification
- Low voiding formulation
- Formulated for fine pitch printing
- Enhanced fine pitch and stencil life

DSP 718D Water-Soluble Solder Paste Syringe Dispensing

Alloys: SAC alloys, Sn96.5/Ag3.5, Sn100e, Sn42/Bi58

- ORH0 Flux classification
- Easily dispensed
- Yields bright, shiny joints
- Designed specifically for lead-free applications

DSP 315D R.A. Solder Paste Syringe Dispensing

(Alloys: SAC alloys)

- ROM0 Flux classification
- Superior wettability
- Hard, non-conductive residues
- Available in both leaded and lead-free solder paste

DSP 800LF No-Clean Solder Paste Stencil Printing

Alloy: Sn100e Sn/Cu/Co Low Cost Lead Free Alloy

- ROL0 Flux classification
- Halogen-Free
- Lower cost alloy compared to SAC alloys
- Pin testable residue

DSP 700LF Water-Soluble Solder Paste Stencil Printing

Alloy: Sn100e Sn/Cu/Co Low Cost Lead Free Alloy

- ORH0 Flux classification
- Excellent wettability
- Lower cost alloy compared to SAC alloys
- Residues easily removed

Leaded Formulations:

DSP 6701 No-Clean Solder Paste Stencil Printing

Alloys: Sn63/Pb37, Sn62/Pb36/Ag2, Sn10/Pb88/Ag2

- REL0 Flux classification
- Robust Sn/Pb formulation
- Low residue
- Non-conductive residues

DSP XP692 No-Clean Solder Paste Stencil Printing

Alloys: Sn63/Pb37, Sn62/Pb36/Ag2

- REL0 Flux classification
- Excellent wettability
- Extended stencil time
- Soft, non-tacky residue

DSP 691A No-Clean Solder Paste Stencil Printing

Alloys: Sn63/Pb37

- REL0 Flux classification
- Pin testable
- Low residue
- Excellent wetting on OSP surfaces

DSP 699 No-Clean Solder Paste Stencil Printing

Alloys: Sn63/Pb37

- Excellent wetting and coalescence for fine pitch
- ROL0 Flux classification
- Halogen-Free
- Low voiding

DSP 615D No-Clean Solder Paste Syringe Dispensing

Alloys: Sn63/Pb37, Sn62/Pb36/Ag2

- REL0 Flux classification
- Hard, non-conductive residues

DSP 619D No-Clean Solder Paste Syringe Dispensing

Alloys: Sn63/Pb37

- REL0 Flux classification
- Transparent residue
- Pin testable post solder residue

Particle Size Chart

Mesh Size	Microns Size	Particle Type
-200+325	75-45	2
-325+500	45-25	3
-400+635	38-20	4
-500	25-15	5
-635	15-5	6

Paste Packaging Options

Type Designation	Description	Net Weight
Jar	3 - 4 oz., Jar	250 - 500 grams
Semco Cartridges	6 oz., Cartridge 12 oz., Cartridge	500 - 700 grams 1000 - 1400 grams
Syringe	10cc., Syringe 30cc., Syringe	35 grams 100 grams

DSP 788 Water-Soluble Solder Paste Stencil Printing

Alloys: Sn63/Pb37, Sn62/Pb36/Ag2

- ORL0 Flux classification
- Non-hygroscopic
- Long stencil life
- Easy removal of residues

DSP 792 Water-Soluble Solder Paste Stencil Printing

Alloys: Sn63/Pb37

- ORM0 Flux classification
- Halide-Free
- Ultra-fine pitch printing with Type 3, 4 and 5 powder
- Yields bright, shiny joints

DSP 798 Water-Soluble Solder Paste Stencil Printing

Alloys: Sn63/Pb37, Sn62/Pb36/Ag2

- ORL0 Flux classification
- Pin testable
- Low residue
- Excellent wetting on OSP surfaces

DSP XP799 Water-Soluble Solder Paste Stencil

Alloys: Sn63/Pb37, Sn62/Pb36/Ag2

- ORL1 Flux classification
- Extended stencil life
- Excellent wetting on OSP surfaces
- Residues easily cleaned

DSP 717D Water-Soluble Solder Paste Dispensing

Alloys: Sn63/Pb37, Sn96.5/Ag3.5

- ORL0 Flux classification
- Halogen-Free dispensing paste

DSP 230 R.M.A. Solder Paste Stencil Printing

Alloy: Sn63/Pb37

- ROM0 Flux classification
- Designed for fine pitch printing
- Yields bright, shiny joints

DSP 215D R.M.A. Solder Paste Syringe Dispensing

Alloy: Sn63/Pb37

- ROM0 Flux classification
- Easily dispensed
- Hard, non-conductive residues

DSP 350 R.A. Solder Paste Stencil Printing

Alloy: Sn63/Pb37

- ROM1 Flux classification
- Excellent wettability
- Robust Sn/Pb formulation
- Non-corrosive residues

DSP 315D Solder Paste Syringe Dispensing

Alloy: Sn63/Pb37

- ROM0 Flux classification
- Superior wettability
- Hard, non-conductive residues

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- Singapore - Philippines -

Home Of Delta Solder Paste
www.qualitek.com